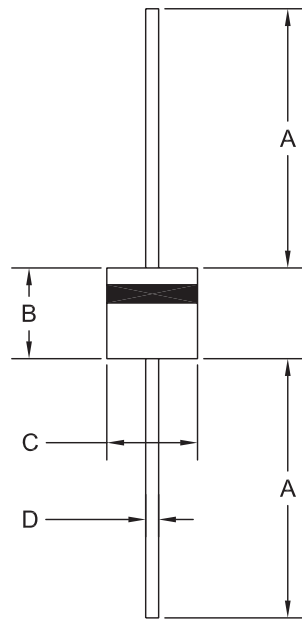


Package Details - Case 106

Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.000	-	25.40	-
B	0.340	0.360	8.64	9.14
C	0.340	0.360	8.64	9.14
D	0.048	0.053	1.22	1.35

CASE 106 (REV: R1)

Lead Code:
Cathode band

R1

Packing options:

Bulk - Packing Code: D

D = White corrugated box with black conductive coating (surface resistivity of $<10^5$ ohms per square).

Bulk Packing Quantity: 250

Tape and Reel - Packing Code: A

A = Axial taped and reeled in accordance with EIA-296-E. If required, individual reels placed in poly antistatic coated bags (surface resistivity of $>10^9$ and $<10^{13}$ ohms per square).

Tape and Reel Packing Quantity: 800

Material Composition Specification

CASE 106



Device average mass 1.95 g

Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.29%	5.71	Si	7440-21-3	0.28%	5.43	2,785
				Pb	7439-92-1	0.01%	0.28	144
die attach	high temperature solder	0.57%	11.11	Pb	7439-92-1	0.53%	10.275	5,269
				Sn	7440-31-5	0.03%	0.556	285
				Ag	7440-22-4	0.01%	0.279	143
leadframe	Cu alloy	54.1%	1055	Cu	7440-50-8	54.05%	1054	540,513
				Fe	7439-89-6	0.05%	1.0	513
encapsulation*	EMC	41.4%	807.6	silica	7631-86-9	31.87%	621.37	318,651
				epoxy resin	29690-82-2	4.14%	80.76	41,415
				phenol resin	9003-35-4	4.01%	78.29	40,149
				Sb2O3	1309-64-4	0.70%	13.59	6,969
				Br	7726-95-6	0.70%	13.59	6,969
	EMC GREEN	41.4%	807.6	silica	7631-86-9	31.89%	621.85	318,897
				epoxy resin	29690-82-2	4.14%	80.76	41,415
				phenol resin	9003-35-4	4.02%	78.337	40,173
				carbon black	1333-86-4	0.12%	2.423	1,243
				metal hydroxide	1309-42-8	1.24%	24.23	12,426
plating**	tin/lead process	3.62%	70.55	Sn	7440-31-5	2.89%	56.44	28,944
				Pb	7439-92-1	0.72%	14.11	7,236
	matte tin	3.62%	70.55	Sn	7440-31-5	3.62%	70.55	36,179
ink	N/A	0.0015%	0.03	2-propenic acid	53192-18-0	0.001%	0.0204	10
				Al	7429-90-5	0.0003%	0.0054	3
				silica	112945-52-5	0.00005%	0.0009	0.5
				methanone	947-19-3	0.00005%	0.0009	0.5
				isoamyl 4-benzoate	21245-01-2	0.0001%	0.0024	1

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "PB FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (16-July 2018)